

GBJ8005G~GBJ810G

Rev.A .Jul.-2018



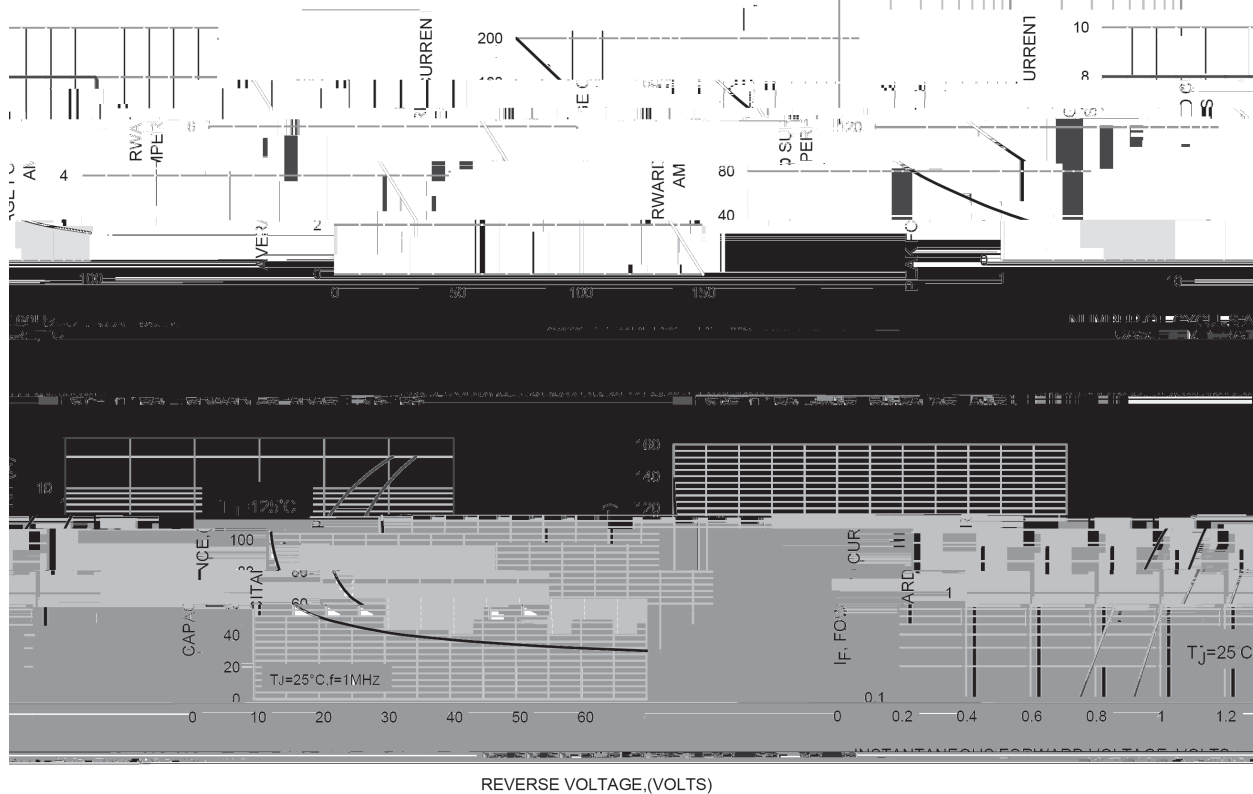
蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

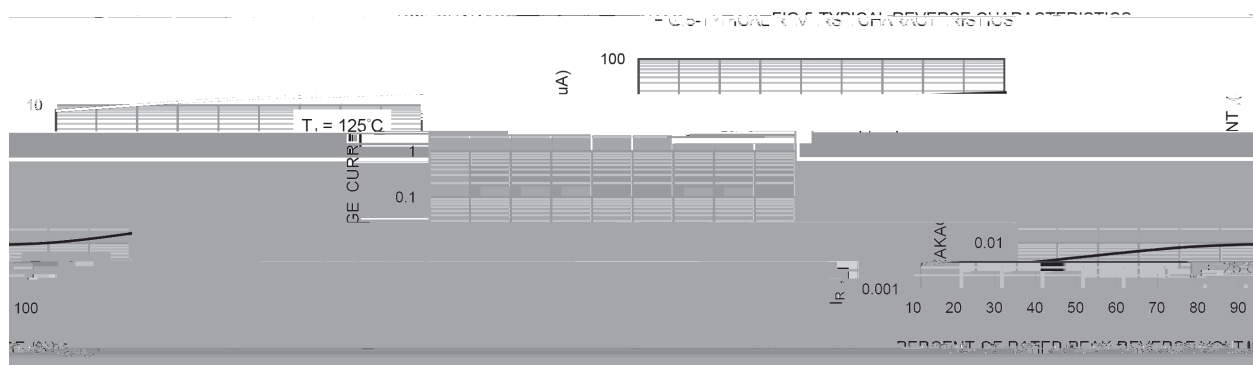
Parameter	Symbol	Rating							Unit
		GBJ 8005G	GBJ 801G	GBJ 802G	GBJ 804G	GBJ 806G	GBJ 808G	GBJ 810G	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current (with heatsink Note 2)	$I_{F(AV)}$	8.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	200							A
I^2t Rating for Fusing (t<8.3ms) Typical Junction	I^2t	166							A ² s

/ Electrical Characteristic Curve

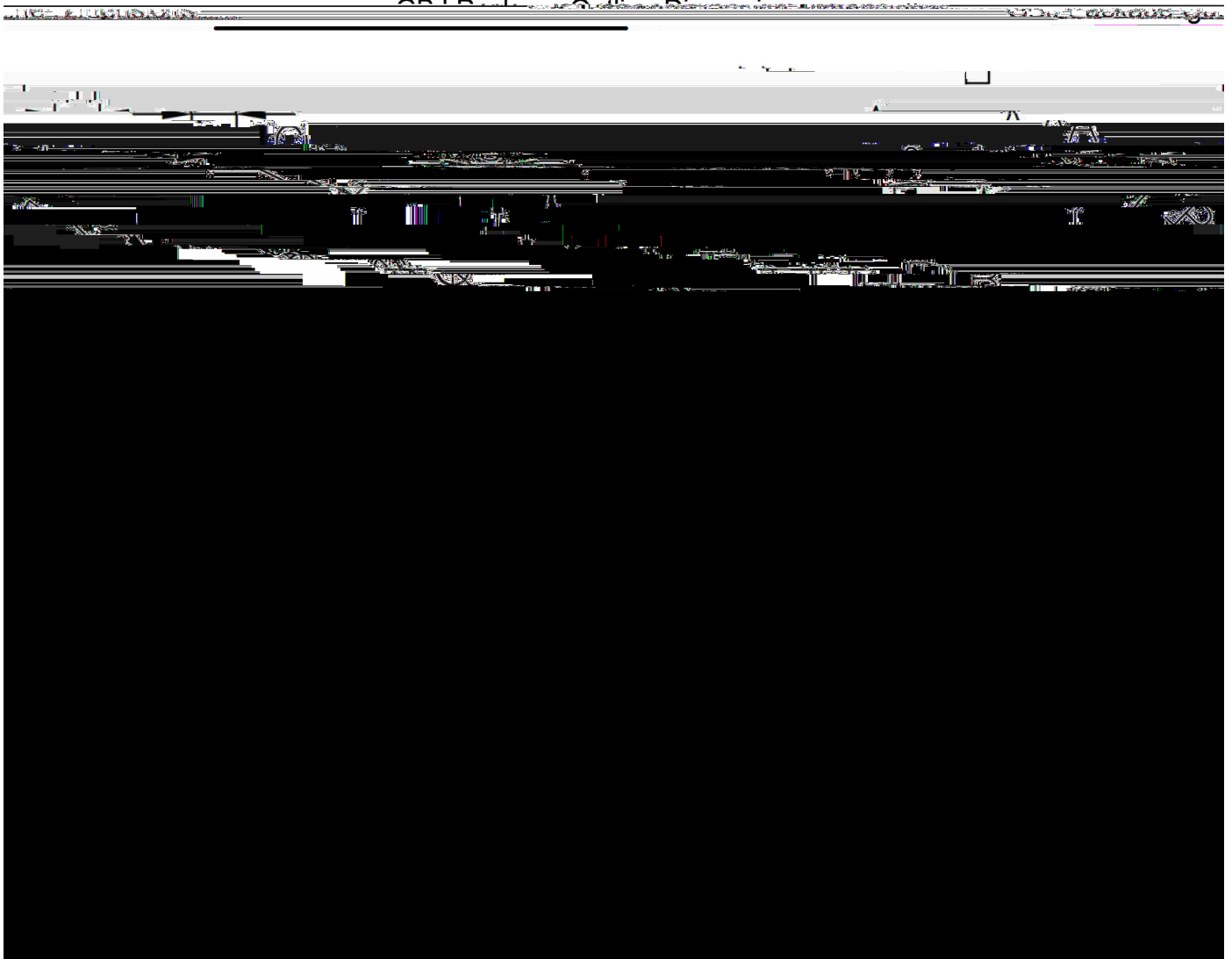
FIG.1-FORWARD CURRENT DERATING CURVE



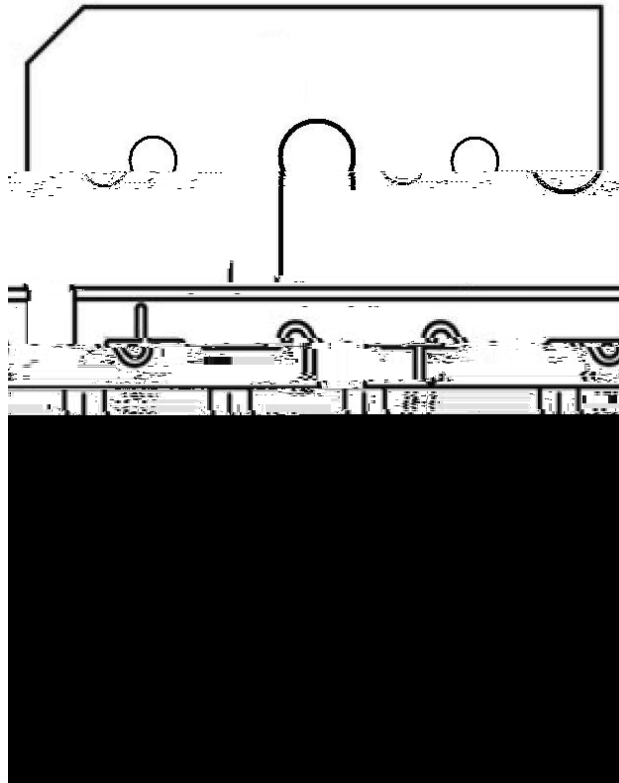
REVERSE VOLTAGE,(VOLTS)



/ Package Dimensions



/ Marking Instructions



б " X

JEM;338J X

м F β з N

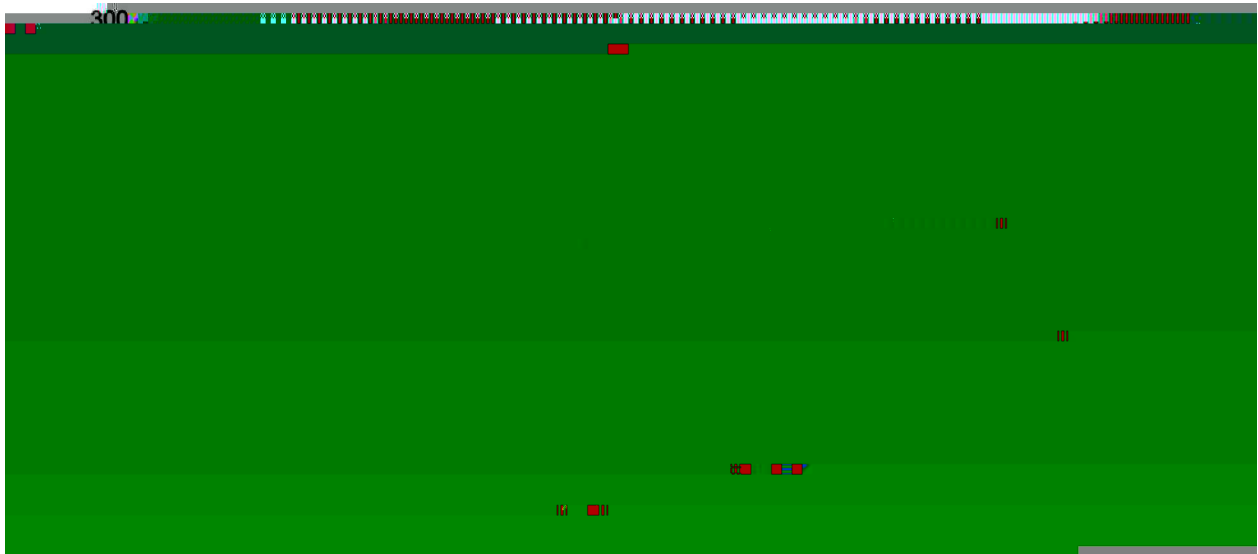
---- X

м 1 F ђ N П 1 4 1 F ђ N Ψ ρ

Qrwh=



() / Temperature Profile for Dip Soldering(Pb-Free)



1. 25~150 °C

1. 25~150 °C, Time: 60~90sec;

2. 255 °C, Time: 5~10sec;

3. Cooling Speed: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.

2. Peak Temp.: 255 °C, Duration: 5~10sec.

3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

270 ± 5 °C

10 ± 1 sec.

Temp.: 270 ± 5